# ZESTRON® SD 301

## Cleaning medium for the removal of solder pastes, SMT adhesives and thick film pastes from stencils and screens

ZESTRON® SD 301 is an improved version of ZESTRON® SD 300 with reduced odor. The solvent-based cleaner removes solder pastes, SMT adhesives as well as thick film pastes from stencils and screens in spray-in-air systems. A faster drying time allows for shorter cleaning processes. Its high flash point permits both, manual usage and the application in printers and stencil cleaning equipment.

| **Areas of application: Stencil / Misprinted Board Cleaning** | | **Additional product information:** |
|---|---|---|
| SMT or conductive adhesives | ++ | **Application Recommendation:** Specific parameters for your cleaning process<br><br>**Technical Information Sheet 2:** Overview of pastes and fluxes tested<br><br>**Technical Information Sheet 3:** Material compatibility overview |
| Thick film pastes | ++ | |
| Low solid flux residues | o | |
| Solder paste (unsoldered) | ++ | |
| Rosin-based flux residues | + | |
| Water soluble flux residues | o | |

++ highly recommended, best results  + recommended  0 possible

**Technical Centers - ① America ② Europe ③ Malaysia ④ East China ⑤ South China**
**Cleaning Process Solutions under Production Floor Conditions**


Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +1 (703) 393-9880; Email: infoUSA@zestron.com

## Advantages compared to other surfactant cleaners:

- Wide process window facilitates the removal of solder pastes, SMT adhesives and resistor pastes from stencils and screens as well as flux residues from misprinted assemblies.
- High loading capabilities, long bath life and therefore low cleaning costs.
- Due to a high flash point of 47°C / 117°F ZESTRON® SD 301 and can be used in non-heated equipment without external explosion-protection systems.
- Non-halogenated, organic solvent-based cleaning agent.
- Used at ambient cleaning temperatures.
- Low odor, fast drying time.

Please refer to the material compatibility datasheet (Technical Information 3) prior to cleaning plastics.



ITAR registered to comply with the U.S. Government regulations



TECHNICAL INFORMATION 1

ZESTRON
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America
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South Asia
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infochina@zestron.com

| Process | 1. Cleaning | 2. Rinsing | 3. Drying |
|---|---|---|---|
| Spray-in-air | ZESTRON® SD 301 | ZESTRON® SD 301 | Circulating or compressed air |

| Technical Data | | |
|---|---|---|
| Density | g/ccm at 20°C / 68°F | 0.88 |
| Surface tension | mN/m at 25°C / 77°F | 26.0 |
| Boiling range | °C/°F | 150 - 170 / 302 - 338 |
| Flash point | °C/°F | 47 / 117 |
| pH-value | 10g/l $H_2O$ | Neutral |
| Vapor pressure | (mbar) at 20°C/68°F | 2 |
| Cleaning temperature | °C/°F | Room temperature |
| Solubility in water | | Soluble |
| Application concentration | Ready to use | Pure |
| HMIS rating | Health-Flammability-Reactivity | 1 - 2 - 0 |

## PRODUCT FEATURES

Extensively tested and suitable for cleaning of lead-free solder pastes

100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

### Environmental, health and safety regulations:

- ZESTRON® SD 301 does not contain halogenated compounds and is biodegradable.
- Water rinsing is not necessary. This results in the elimination of waste water.

### Availability:

- ZESTRON® SD 301 is available in 1L , 5L or 25L containers and 200L drums.

### Storage:

- Store ZESTRON® SD 301 in the original container at a temperature between 5-30°C / 41-86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

### Alternative product recommendation:

- For the water-based cleaning of stencils, we recommend the MPC® based product VIGON® SC 200.